CLAIMS

1. A pressure sensitive adhesive film used to temporarily fix electronic components when sealing the electronic components with a sealing material in an electronic device manufacturing step, the film comprising:

a pressure sensitive adhesive resin layer (A) for temporarily fixing the electronic components;

a pressure sensitive adhesive resin layer (B) used for attaching to a support substrate and of which an adhesive force is decreased by an external stimulus; and

an intermediate layer (C) provided between the pressure sensitive adhesive resin layer (A) and the pressure sensitive adhesive resin layer (B),

wherein a storage elastic modulus E' at 120°C of the intermediate layer (C) is 1.0×10^5 Pa or more and 8.0×10^6 Pa or less, and a loss tangent (tan δ) at 120°C of the intermediate layer (C) is 0.1 or less.

2. The pressure sensitive adhesive film according to claim 1,

wherein the adhesive force of the pressure sensitive adhesive resin layer (B) is decreased by heating.

3. The pressure sensitive adhesive film according to claim 2,

wherein the pressure sensitive adhesive resin layer (B) includes at least one selected from a gas generating component and heat-expandable microspheres.

4. The pressure sensitive adhesive film according to any one of claims 1 to 3,

wherein a content of at least one selected from a gas generating component and heat-expandable microspheres in the pressure sensitive adhesive resin layer (A) is 0.1% by mass or less when the entire pressure sensitive adhesive resin layer (A) is defined as 100% by mass.

5. The pressure sensitive adhesive film according to any one of claims 1 to 3,

wherein the sealing material is an epoxy resin-based sealing material.

6. The pressure sensitive adhesive film according to any one of claims 1 to 3,

wherein the pressure sensitive adhesive resin layer (A) includes a (meth)acrylic pressure sensitive adhesive resin.

7. A method for manufacturing an electronic device comprising at least:

a step (1) of preparing a structure having the pressure sensitive adhesive film according to any one of claims 1 to 3, an electronic component attached to the pressure sensitive adhesive resin layer (A) of the pressure sensitive adhesive film, and a support substrate attached to the pressure sensitive adhesive resin layer (B) of the pressure sensitive adhesive film;

a step (2) of sealing the electronic component with a sealing material;

a step (3) of peeling the support substrate from the structure by decreasing an adhesive force of the pressure sensitive adhesive resin layer (B) by applying an external stimulus; and

a step (4) of peeling the pressure sensitive adhesive film from the electronic component.

8. The method for manufacturing an electronic device according to claim 7, wherein the sealing material is an epoxy resin-based sealing material.